



600V Super-junction Power MOSFET

DESCRIPTION

600V Super-junction Power MOSFET

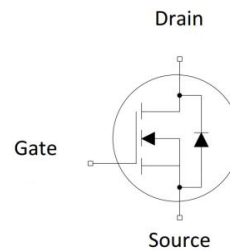
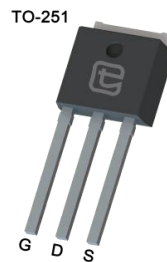
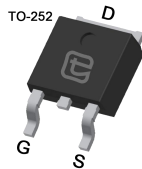
Super-junction power MOSFET is a revolutionary technology for high voltage power MOSFETs, designed according to the SJ principle. The Multi-EPI SJ MOSFET provide an extremely low switching, commutation and conduction losses device with highest robustness make especially resonant switching applications more reliable, more efficient, lighter and cooler, designed by Wuxi Unigroup Microelectronics Company.

FEATURES

- Very low FOM $R_{DS(on)} \times Q_g$
- 100% avalanche tested
- Easy to use/drive
- RoHS compliant

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- Charger



Device Marking and Package Information

Device	Package	Marking
TPA60R530M	TO-220F	60R530M
TPD60R530M	TO-252	60R530M
TPU60R530M	TO-251	60R530M

Key Performance Parameters

Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	600	V
$R_{DS(on),max}$	0.53	Ω
I_D	7	A
$Q_{g,typ}$	13.8	nC
I_{DM}	21	A



Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted				
Parameter	Symbol	Value		Unit
		TO-220F	TO-252/TO-251	
Drain-Source Voltage ($V_{GS} = 0\text{V}$)	V_{DSS}	600		V
Continuous Drain Current	I_D	$T_C = 25^\circ\text{C}$	7	A
		$T_C = 100^\circ\text{C}$	4.2	
Pulsed Drain Current (note1)	I_{DM}	21		A
Gate-Source Voltage	V_{GSS}	± 30		V
Single Pulse Avalanche Energy (note2)	E_{AS}	142		mJ
Repetitive Avalanche Energy (note2)	E_{AR}	0.21		mJ
Avalanche Current	I_{AR}	1.3		A
MOSFET dv/dt ruggedness, $V_{DS} = 0 \dots 480\text{V}$	dv/dt	50		V/ns
Power Dissipation	P_D	28	63	W
Continuous Body Diode Current	I_S	6		A
Pulsed Diode Forward Current (note1)	I_{SM}	21		
Reverse diode dv/dt (note3)	dv/dt	15		V/ns
Maximum diode commutation speed (note3)	di_f/dt	500		A/us
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55~+150		$^\circ\text{C}$

Thermal Resistance				
Parameter	Symbol	Value		Unit
		TO-220F	TO-252/TO-251	
Thermal Resistance, Junction-to-Case	R_{thJC}	4.5	2.0	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient	R_{thJA}	80	62	



Specifications $T_J = 25^{\circ}\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	600	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 600V, V_{GS} = 0V, T_J = 25^{\circ}\text{C}$	--	--	1	μA
		$V_{DS} = 600V, V_{GS} = 0V, T_J = 150^{\circ}\text{C}$	--	--	100	
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 30V$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.5	--	4.0	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 3.5A$	--	0.46	0.53	Ω
Gate resistance	R_G	$f = 1.0\text{MHz}$ open drain	--	7	--	Ω
Dynamic						
Input Capacitance	C_{iss}	$V_{GS} = 0V,$ $V_{DS} = 100V,$ $f = 1.0\text{MHz}$	--	526	--	μF
Output Capacitance	C_{oss}		--	27	--	
Reverse Transfer Capacitance	C_{rss}		--	1.6	--	
Total Gate Charge	Q_g	$V_{DD} = 480V, I_D = 7A,$ $V_{GS} = 10V$	--	13.8	--	nC
Gate-Source Charge	Q_{gs}		--	2.8	--	
Gate-Drain Charge	Q_{gd}		--	5.6	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 400V, I_D = 7A,$ $R_G = 25\Omega$	--	53	--	ns
Turn-on Rise Time	t_r		--	60	--	
Turn-off Delay Time	$t_{d(off)}$		--	102	--	
Turn-off Fall Time	t_f		--	52	--	
Drain-Source Body Diode Characteristics						
Body Diode Voltage	V_{SD}	$T_J = 25^{\circ}\text{C}, I_{SD} = 3.5A, V_{GS} = 0V$	--	0.9	1.2	V
Reverse Recovery Time	t_{rr}	$V_R = 400V, I_F = 7A,$ $di_F/dt = 100A/\mu s$	--	321	--	ns
Reverse Recovery Charge	Q_{rr}		--	3.4	--	μC
Peak Reverse Recovery Current	I_{rrm}		--	21	--	A

Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $I_{AS} = 1.3A, V_{DD} = 50V, R_G = 25\Omega$, Starting $T_J = 25^{\circ}\text{C}$
3. Identical low side and high side switch with identical R_G



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

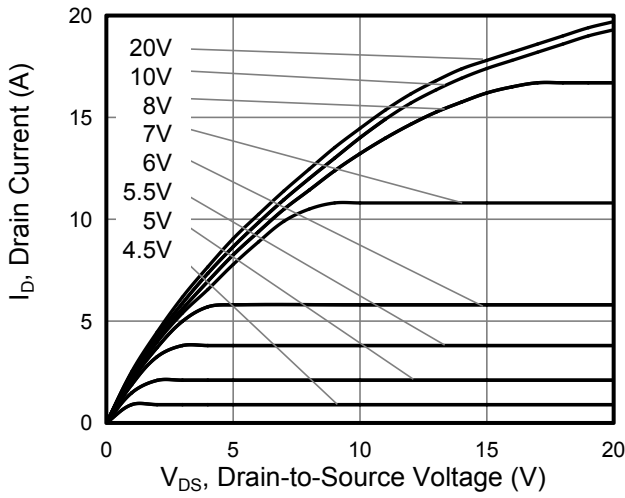


Figure 2. Transfer Characteristics

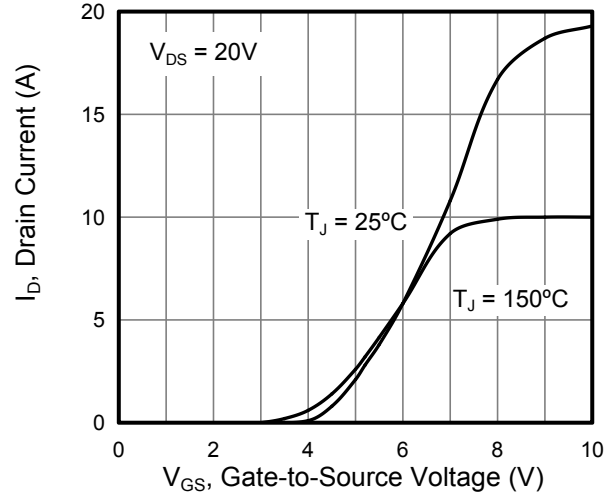


Figure 3. On-Resistance vs. Drain Current

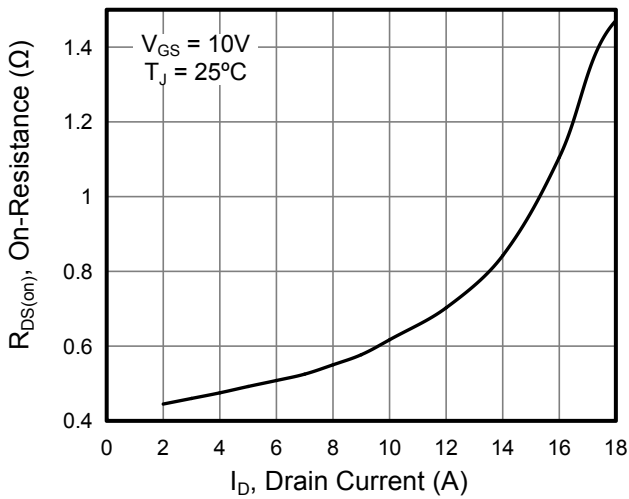


Figure 4. Capacitance

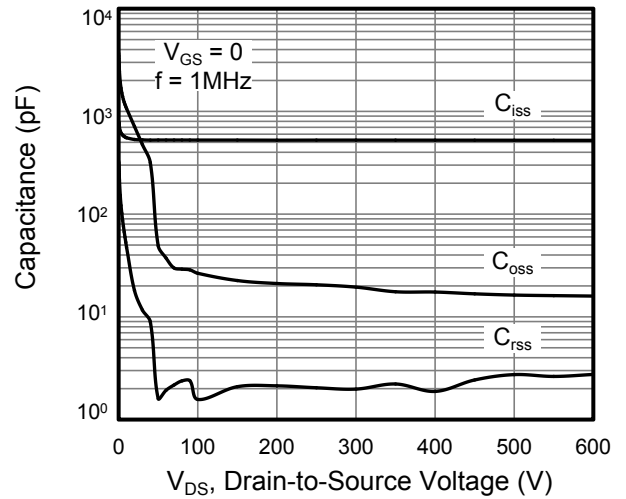


Figure 5. Gate Charge

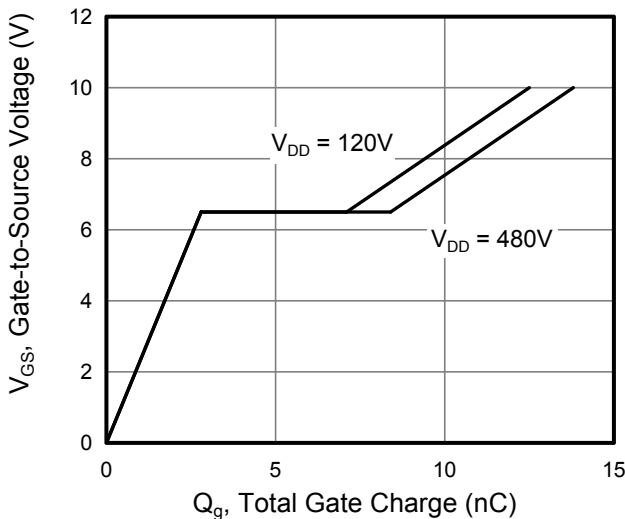
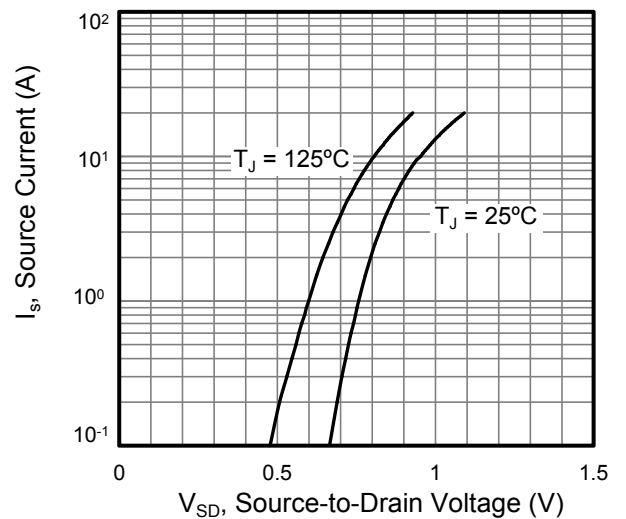


Figure 6. Body Diode Forward Voltage





Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. On-Resistance vs. Junction Temperature

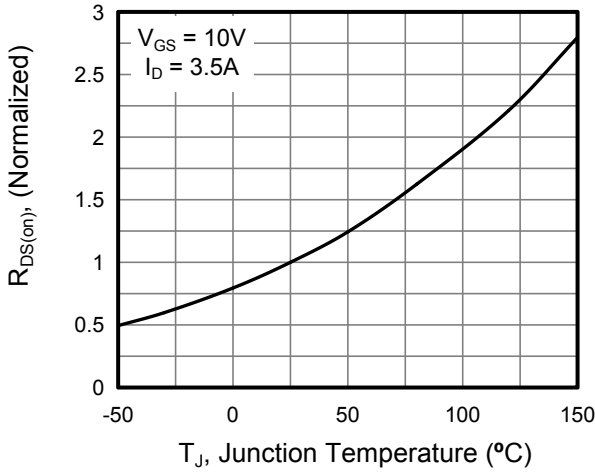


Figure 8. Breakdown voltage vs. Junction Temperature

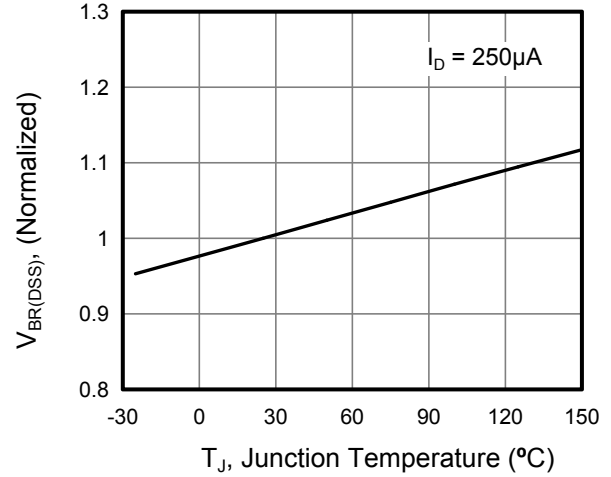


Figure 9. Transient Thermal Impedance TO-220F

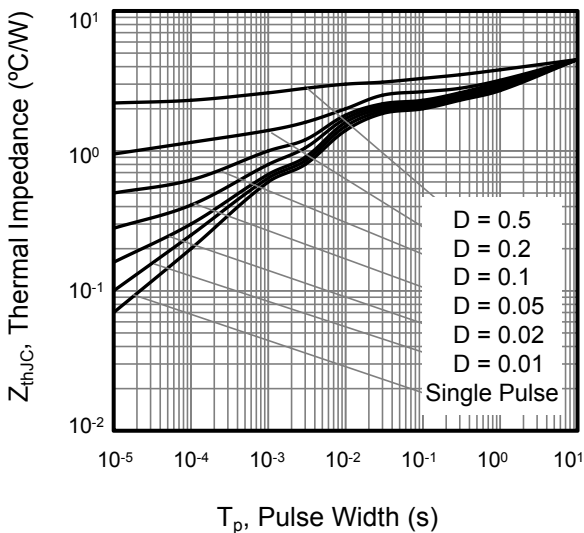


Figure 10. Safe operation area for TO-220F

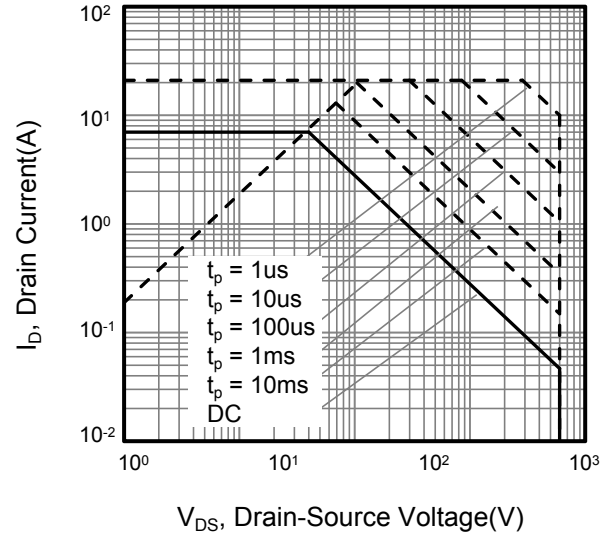


Figure 11. Transient Thermal Impedance TO-252/TO-251

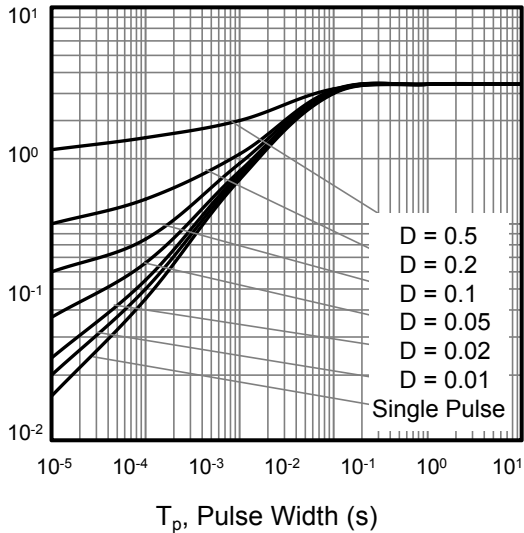


Figure 12. Safe operation area for TO-252/TO-251

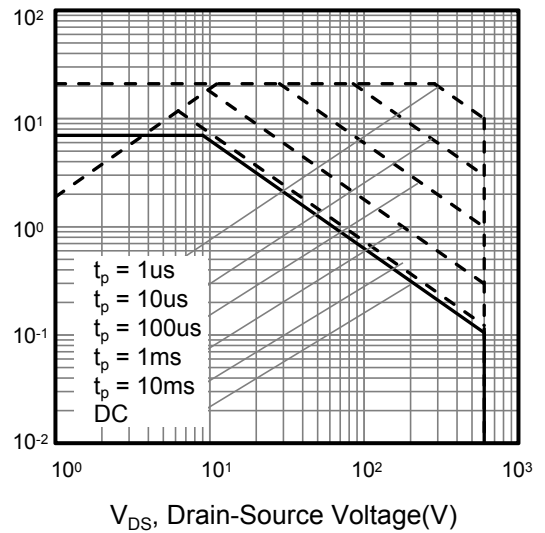




Figure A: Gate Charge Test Circuit and Waveform

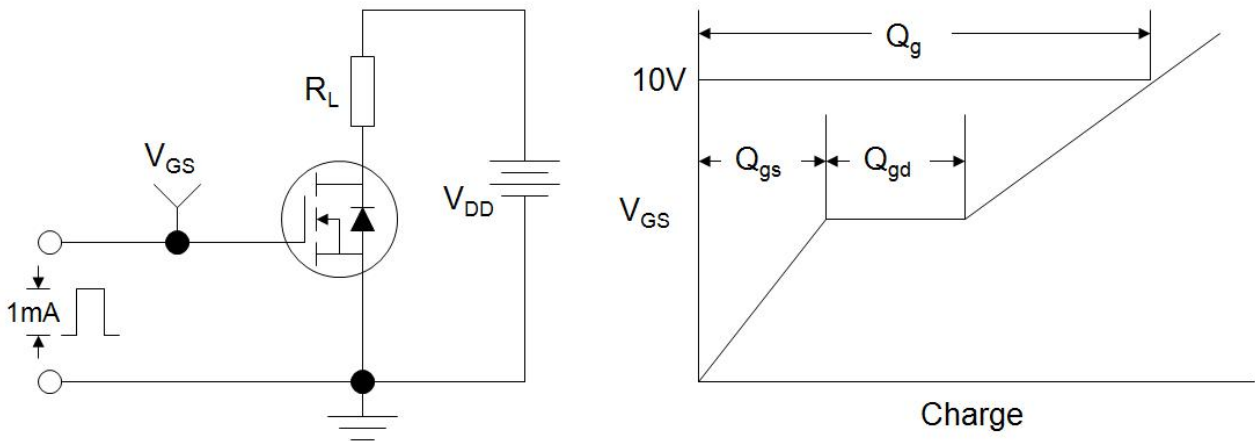


Figure B: Resistive Switching Test Circuit and Waveform

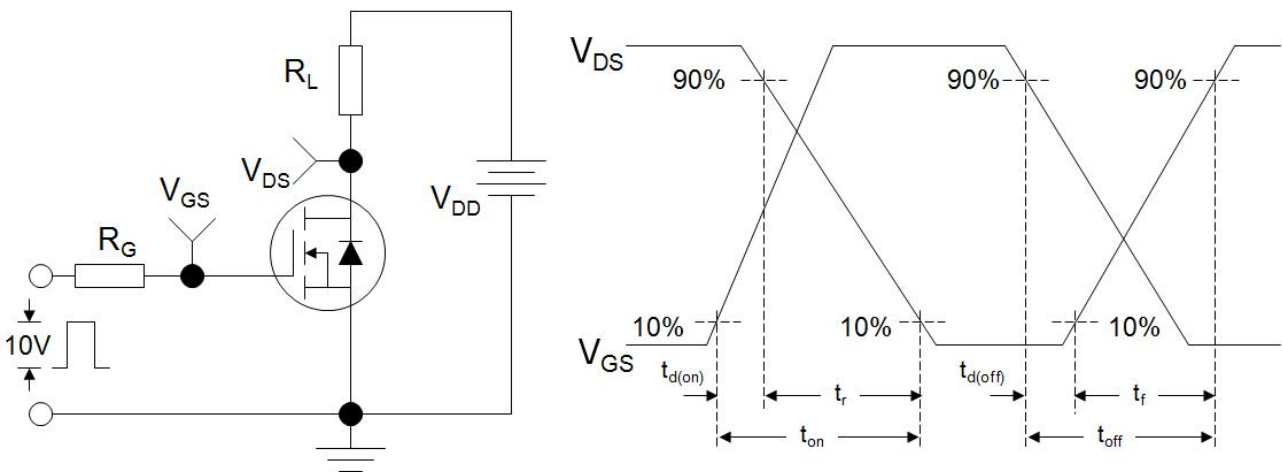
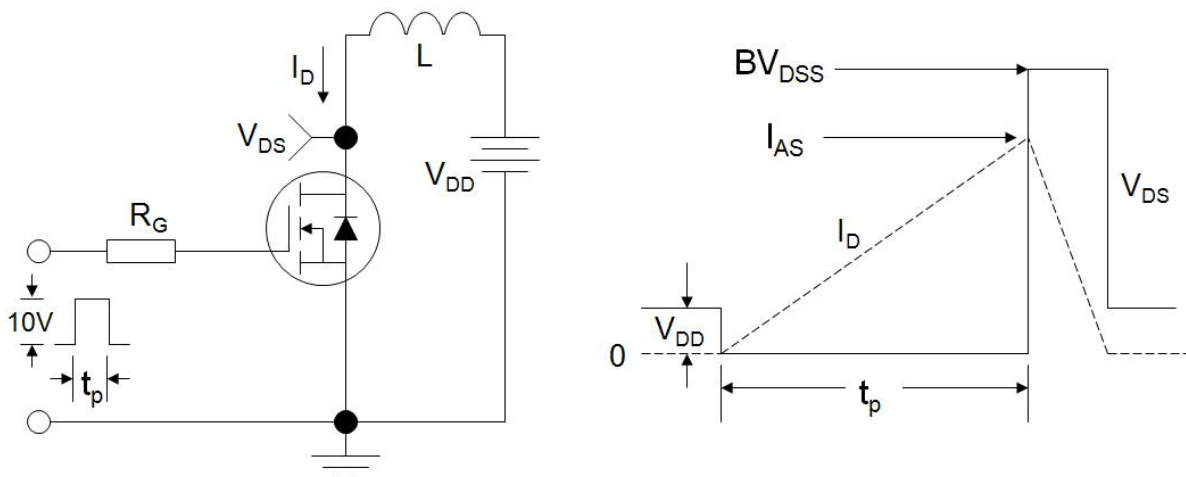
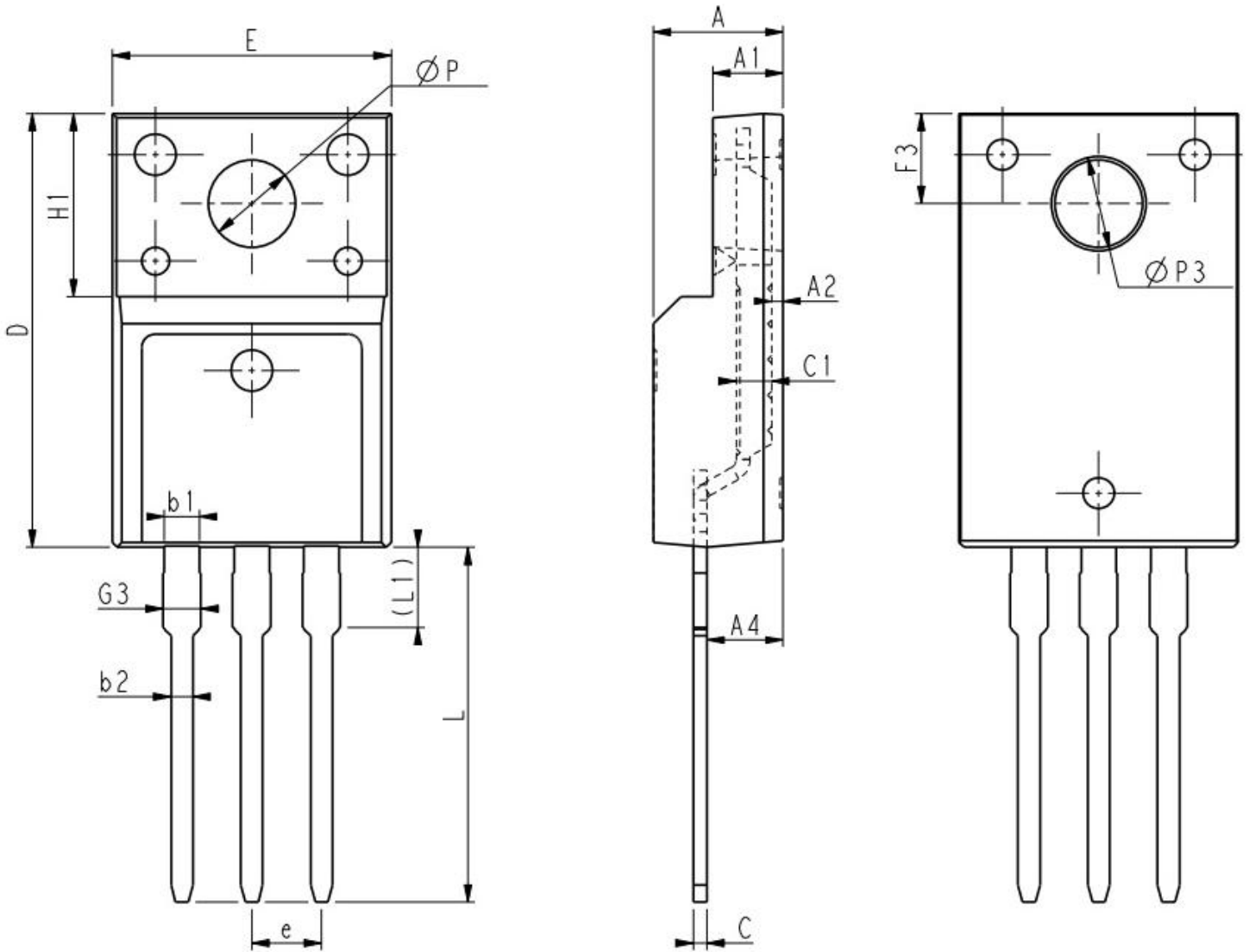


Figure C: Unclamped Inductive Switching Test Circuit and Waveform





TO-220F

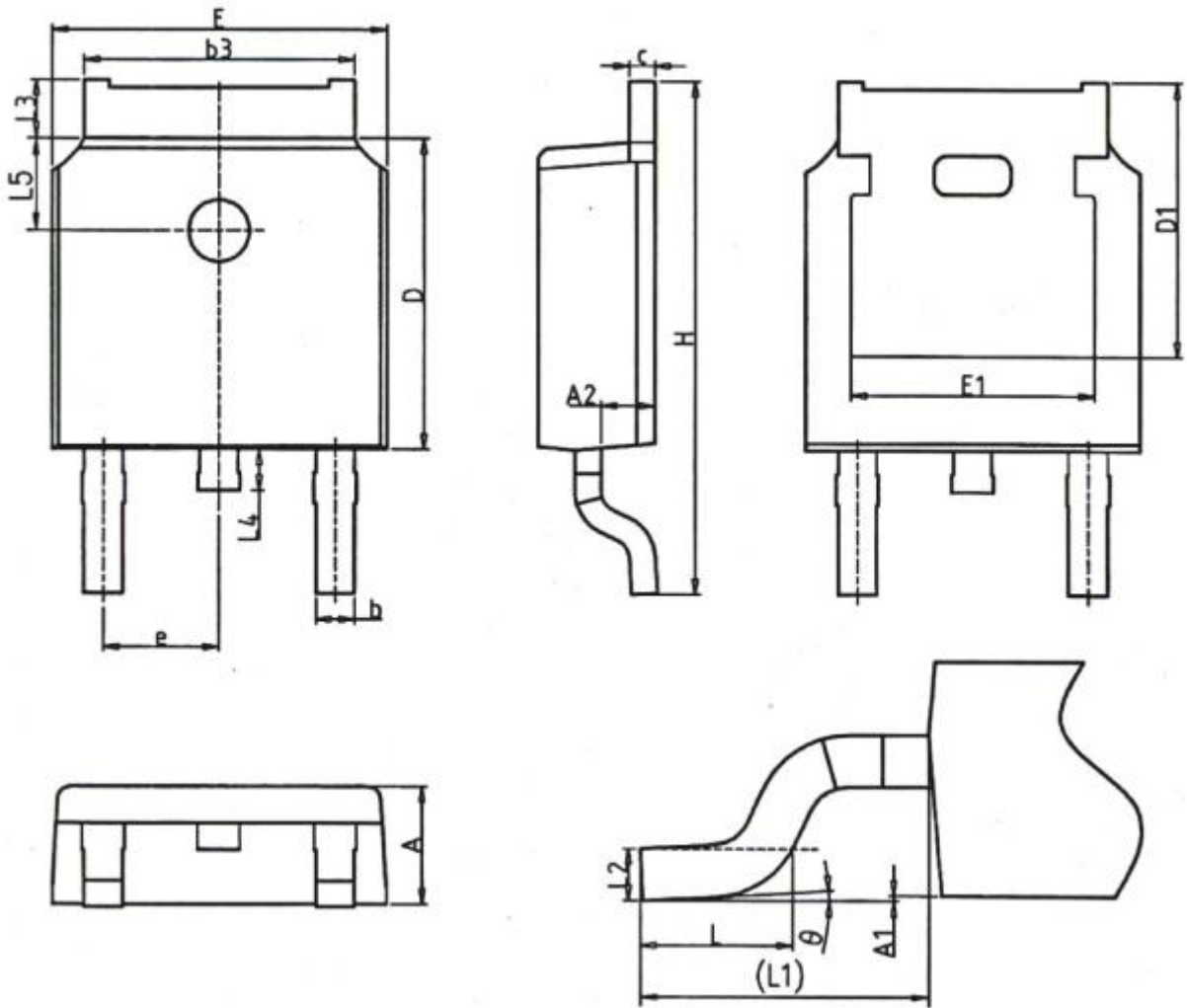


Unit:mm			
Symbol	Min.	Nom	Max.
E	9.96	10.16	10.36
A	4.50	4.70	4.90
A1	2.34	2.54	2.74
A2	0.30	0.45	0.60
A4	2.56	2.76	2.96
c	0.40	0.50	0.65
c1	1.20	1.30	1.35
D	15.57	15.87	16.17
H1	6.70REF		

Unit:mm			
Symbol	Min.	Nom	Max.
e	2.54BSC		
L	12.68	12.98	13.28
L1	2.93	3.03	3.13
ΦP	3.03	3.18	3.38
$\Phi P3$	3.15	3.45	3.65
F3	3.15	3.30	3.45
G3	1.25	1.35	1.55
b1	1.18	1.28	1.43
b2	0.70	0.80	0.95



TO-252

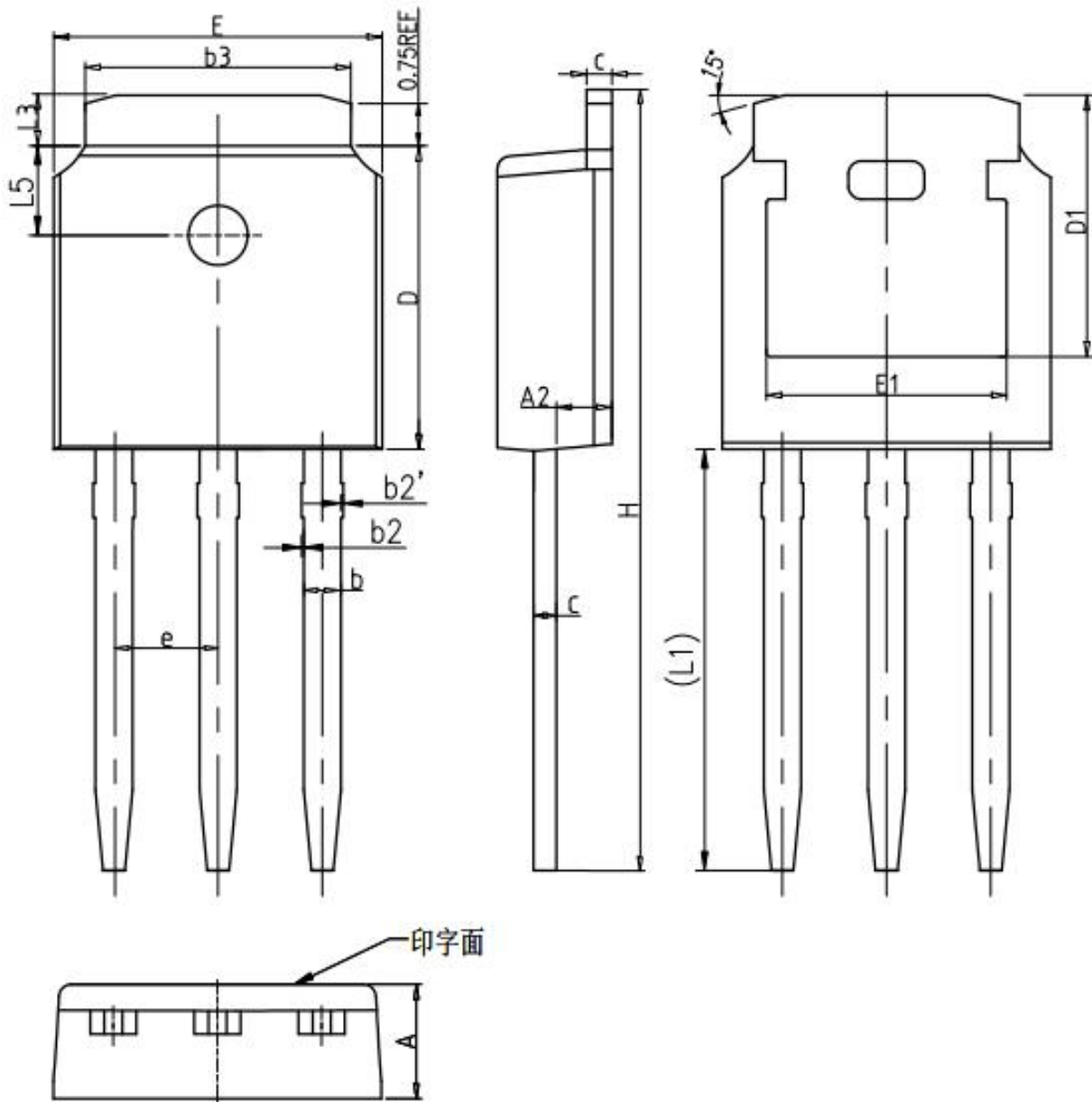


Unit:mm			
Symbol	Min.	Nom	Max.
A	2.20	2.30	2.40
A1	0.00	-	0.20
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b3	5.20	5.33	5.50
c	0.43	0.53	0.63
D	5.98	6.10	6.22
D1	5.30 REF		
E	6.40	6.60	6.80
E1	4.63	-	-

Unit:mm			
Symbol	Min.	Nom	Max.
e	2.286 BSC		
H	9.40	10.10	10.50
L	1.38	1.50	1.75
L1	2.90 REF		
L2	0.51 BSC		
L3	0.88	-	1.28
L4	-	-	1.00
L5	1.65	1.80	1.95
θ	0°	-	8°



TO-251



Unit:mm			
Symbol	Min.	Nom	Max.
A	2.20	2.30	2.38
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b2	0.00	0.04	0.10
b2'	0.00	0.04	0.10
b3	5.20	5.33	5.46
c	0.43	0.53	0.61
D	5.98	6.10	6.22

Unit:mm			
Symbol	Min.	Nom	Max.
D1	5.30 REF		
E	6.40	6.60	6.73
E1	4.63	-	-
e	2.286 BSC		
H	16.22	16.52	16.82
L1	9.15	9.40	9.65
L3	0.88	1.02	1.28
L5	1.65	1.80	1.95



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